
Sixth generation, high speed soft switching series

Maximum Ratings

For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

Parameter	Symbol	Value	Unit
Collector-emitter voltage, $T_{vj} \geq 25^\circ\text{C}$	V_{CE}	1200	V
DC collector current, limited by T_{vjmax} $T_c = 25^\circ\text{C}$ $T_c = 100^\circ\text{C}$	I_C	80.0 40.0	A
Pulsed collector current, t_p limited by T_{vjmax}	I_{Cpuls}	160.0	A
Turn off safe operating area $V_{CE} \leq 1200\text{V}$, $T_{vj} \leq 175^\circ\text{C}$	-	160.0	A
Diode forward current, limited by T_{vjmax} $T_c = 25^\circ\text{C}$ $T_c = 100^\circ\text{C}$	I_F	80.0 40.0	A
Diode pulsed current, t_p limited by T_{vjmax}	I_{Fpuls}	160.0	A
Gate-emitter voltage Transient Gate-emitter voltage ($t_p \leq 0.5\mu\text{s}$, $D < 0.001$)	V_{GE}	± 20 25	V
Power dissipation $T_c = 25^\circ\text{C}$ Power dissipation $T_c = 100^\circ\text{C}$	P_{tot}	500.0 250.0	W
Operating junction temperature	T_{vj}	-40...+175	°C
Storage temperature	T_{stg}	-55...+150	°C
Soldering temperature, wave soldering 1.6mm (0.063in.) from case for 10s		260	°C

Thermal Resistance

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	

R_{th} Characteristics

IGBT thermal resistance, junction - case	$R_{th(j-c)}$		-	-	0.30	K/W
Diode thermal resistance, junction - case	$R_{th(j-c)}$		-	-	0.78	K/W
Thermal resistance junction - ambient	$R_{th(j-a)}$		-	-	40	K/W

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Electrical Characteristic, at $T_{vj} = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Static Characteristic						
Collector-emitter saturation voltage	V_{CEsat}	$V_{GE} = 15.0\text{V}$, $I_C = 40.0\text{A}$ $T_{vj} = 25^\circ\text{C}$ $T_{vj} = 125^\circ\text{C}$ $T_{vj} = 175^\circ\text{C}$	-	1.85	2.15	V
Diode forward voltage	V_F	$V_{GE} = 0\text{V}$, $I_F = 40.0\text{A}$ $T_{vj} = 25^\circ\text{C}$ $T_{vj} = 175^\circ\text{C}$	-	2.20	2.55	V
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C = 1.90\text{mA}$, $V_{CE} = V_{GE}$	5.1	5.7	6.3	V
Zero gate voltage collector current	I_{CES}	$V_{CE} = 1200\text{V}$, $V_{GE} = 0\text{V}$ $T_{vj} = 25^\circ\text{C}$ $T_{vj} = 175^\circ\text{C}$	-	-	850	μA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0\text{V}$, $V_{GE} = 20\text{V}$	-	-	600	nA
Transconductance	g_{fs}	$V_{CE} = 20\text{V}$, $I_C = 40.0\text{A}$	-	32.0	-	S

Electrical Characteristic, at $T_{vj} = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Dynamic Characteristic						
Input capacitance	C_{ies}		-	2700	-	pF
Output capacitance	C_{oes}	$V_{CE} = 25\text{V}$, $V_{GE} = 0\text{V}$, $f = 1\text{MHz}$	-	185	-	
Reverse transfer capacitance	C_{res}		-	120	-	
Gate charge	Q_G	$V_{CC} = 960\text{V}$, $I_C = 40.0\text{A}$, $V_{GE} = 15\text{V}$	-	285.0	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L_E		-	13.0	-	nH

Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic, at $T_{vj} = 25^\circ\text{C}$						
Turn-on delay time	$t_{d(on)}$	$T_{vj} = 25^\circ\text{C}$,	-	27	-	ns
Rise time	t_r	$V_{CC} = 600\text{V}$, $I_C = 40.0\text{A}$, $V_{GE} = 0.0/15.0\text{V}$,	-	27	-	ns
Turn-off delay time	$t_{d(off)}$	$R_{G(on)} = 9.0\Omega$, $R_{G(off)} = 9.0\Omega$, $L_\sigma = 70\text{nH}$, $C_\sigma = 67\text{pF}$	-	315	-	ns
Fall time	t_f	L_σ , C_σ from Fig. E	-	27	-	ns
Turn-on energy	E_{on}	Energy losses include "tail" and diode reverse recovery.	-	1.45	-	mJ
Turn-off energy	E_{off}		-	1.55	-	mJ
Total switching energy	E_{ts}		-	3.00	-	mJ